

Structural characterization of SnO₂ thick film doped with SiC

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ABSTRACT A series of thick film samples with SnO₂ (active material), SiC (dopant) and ethyl cellulose and propylene glycol (organic binder) have been prepared using screen printing method. The thickness of samples prepared is between 1.10±0.01 μm to 2.36±0.01 μm. X-ray analysis has been done using Philips PW Diffractometer. The diffraction peak from the X-ray analysis shows the sample have high degree of crystallinity. The lattice constant calculated for each sample shows that the samples produced has a tetragonal structure and the presence of SiC as dopant did not change the structure of SnO₂.

SnO₂ Thick Film, Screen Printing, Structure, XRD

INTRODUCTION

SnO₂ thick films prepared using various methods have been widely reported [1-4]. Method of producing SnO₂ thick film using screen printing method is very rare [5-6]. In this research screen printing method had been chosen to produce SnO₂ thick film. This method had been used because of low cost, easiness and can be automated [7-8]. In this research the structural properties of SnO₂ thick film doped with SiC will be discussed.

MATERIALS AND METHOD

Screen printing technique has been used in this work to produce SnO₂ thick film sample [9]. Table 1 shows the percentage in weight percent of the composition used to produce the paste. 6% of propylene glycol had been used as organic binder for each sample with the sintering temperature of 600°C for 1 hour.

Table 1: Composition used to produce the screen printing paste.

Sample	Weight Percent (%)		
	SnO ₂	Ethyl cellulose	SiC
S	50	50	0
S1	4.75	4.75	5
S2	45	45	10
S3	42.5	42.5	15
S4	40	40	20

To study the structural characteristic of each sample produced, X-ray diffraction was used. The sample with dimension of 1 cm x 1 cm was prepared on a glass substrate. The sample was then analysed using Philips PW 1390 Diffractometer. This instrument uses Cu Kα ray with the wavelength of 1.5405 Å. The X-ray diffraction data from the samples was then compared with JCPDS. From the X-ray diffraction graph produced, the lattice constant has been calculated using equation (1).

$$d_{hkl} = \sqrt{\frac{h^2 + k^2}{a^2} + \frac{l^2}{c^2}} \quad (1)$$

RESULTS AND DISCUSSION

The diffraction pattern of each sample is shown in Figure 1. d_{hkl} value for all the samples was compared with standard data (JCPDS-ICDD, 1995) to identify the diffraction peak produced by SnO₂ or SiC. Table 2 and 3 show the d_{hkl} values for all the samples studied.

Diffraction peaks for S1 sample having 5 wt.% SiC shows high intensity for SnO₂ with the orientation of (110), (101) and (211). The SiC peaks are obvious but intensity comparison indicates comparatively smaller quantity to that of SnO₂. The lattice constant has been calculated using equation (1). The lattice constant for sample S1 is 4.7414 Å and c is 3.1852 Å.

X-ray diffraction spectrum for sample S2 consisting of 10 wt.% SiC shows changes compared to sample S1. There is an increase of intensity in the peak of SiC with the orientation of (011) with the intensity of 19.2% compared to S1 sample with the intensity of 5.4%. The number of diffraction peaks for SiC also increases compared to S1 sample. This shows that the presence of SiC is clearer with increase in dopant. Lattice constant for S2 sample has been calculated using equation (1). The calculated lattice constants a and c for S2 sample were $a = 4.7344$ Å and $c = 3.1835$ Å.

For S3 sample, consisting of 15 wt.% SiC, dominant diffraction peak for SiC occurs at the orientation of (1011), (0117), (0168), (1136), (2071) and (10127). This shows the increase of SiC peaks compared to S2 sample. Intensity for SiC peaks also increases. Diffraction peak for SnO₂ still shows the highest intensity with the orientation of (110), (101) and (211). This shows that the presence of SiC is much clearer with increase in weight percent of dopant. From the diffraction peak of SnO₂, the lattice constants were calculated. The value of lattice constant for S3 is $a = 4.7511$ Å and $c = 3.1910$ Å.

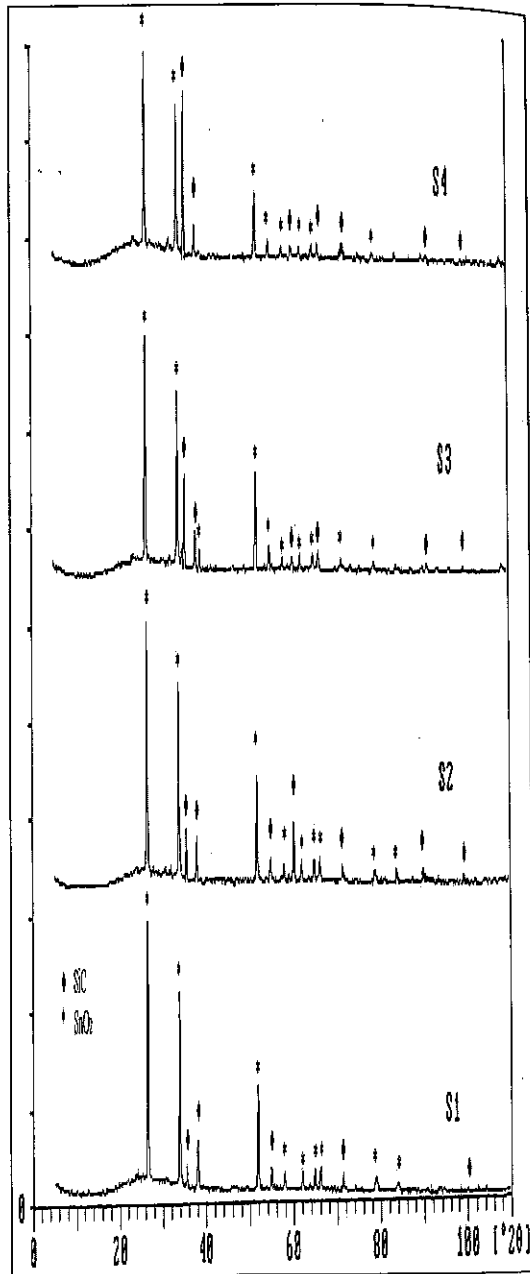


Figure 1. X-ray diffraction spectrum for SnO₂ thick film samples doped with different weight percent of SiC.

Table 2: d_{hkl} value for S1 and S2 samples with 5 wt.% and 10 wt.% of SiC.

Sample and SiC wt. %	d_{hkl} (Å)	I/I ₀ (%)	Identity (hkl)
S1 5 wt.% SiC	3.3527	100	SnO ₂ (110)
	2.6448	73.8	SnO ₂ (101)
	2.5208	5.4	SiC (0117)
	2.3673	17.6	SnO ₂ (111)
	1.7639	40.1	SnO ₂ (211)
	1.674	8.6	SiC (0159)
	1.5930	5.6	SnO ₂ (022)
	1.4978	6.2	SnO ₂ (310)
	1.4423	7.6	SnO ₂ (112)
	1.4148	7.6	SiC (1136)
	1.3212	3	SnO ₂ (202)
	1.2147	4.1	SnO ₂ (321)
	1.532	1.9	SnO ₂ (222)
	0.9491	2.3	SiC (10127)
S2 10 wt.% SiC	3.3477	100	SnO ₂ (110)
	2.6418	79.1	SnO ₂ (101)
	2.5157	19.2	SiC (0117)
	2.3669	17.2	SiC (1025)
	1.7628	42	SnO ₂ (211)
	1.6732	8.8	SnO ₂ (220)
	1.5916	5.8	SnO ₂ (002)
	1.5387	23.3	SiC (0168)
	1.4969	7.0	SnO ₂ (310)
	1.4375	7.7	SnO ₂ (112)
	1.4140	8.6	SnO ₂ (301)
	1.3181	2.5	SnO ₂ (320)
	1.2131	3.8	SnO ₂ (321)
	1.538	3.6	SnO ₂ (222)
1.0798	2.6	SiC (2071)	
0.9490	2.6	SiC (10127)	

Table 3: D_{hkl} value for S3 and S4 samples with 15 wt.% and 20 wt.% of SiC.

Sample and SiC wt. %	d_{hkl} (Å)	I/I ₀ (%)	Identity (hkl)
S3 15 wt.% SiC	2.6490	74.7	SnO ₂ (110)
	2.5708	7.6	SiC (1011)
	2.5229	39.6	SiC (0117)
	2.3723	15.3	SnO ₂ (111)
	1.7657	41.2	SnO ₂ (211)
	1.6759	9.8	SnO ₂ (220)
	1.5944	5.3	SnO ₂ (022)
	1.5408	4.6	SiC (0168)
	1.4993	6.5	SnO ₂ (310)
	1.4388	6.5	SnO ₂ (112)
	1.4150	7.6	SiC (1136)
	1.3221	3.3	SnO ₂ (202)
	1.2151	3.4	SnO ₂ (321)
	1.0805	2.0	SiC (2071)
0.9494	2.3	SiC (10127)	
S4 20 wt.% SiC	2.6452	76.6	SnO ₂ (110)
	2.5215	82.9	SiC (0117)
	2.3702	14.7	SiC (1025)
	1.7646	34.2	SnO ₂ (211)
	1.6749	8.7	SnO ₂ (220)
	1.5920	4.8	SnO ₂ (002)
	1.5409	5.4	SiC (0168)
	1.4971	4.6	SnO ₂ (310)
	1.4384	6.9	SnO ₂ (112)
	1.4147	7.2	SiC (1136)
	1.3161	3.2	SiC (2017)
	1.2144	3.0	SnO ₂ (321)
	1.0802	2.2	SiC (2071)
	0.9495	1.9	SiC (10127)

Figure 1 shows that the diffraction for S4 sample with 20 wt.% of SiC. There is an increase of SiC peak with an increasing intensity. SnO₂ diffraction peak still shows high intensity peak with the orientation of (110), (101) and (211). SiC diffraction peak is much more clear showing the presence of SiC in the sample. Lattice constant values for S4 sample were, $a = 4.7431$ Å and $c = 3.1798$ Å.

CONCLUSIONS

SnO₂ thick film doped with SiC and sintered at 600 °C for 1 hour had been analysed through X-ray diffraction spectrum (XRD). The presence of diffraction peaks for each sample shows that it has high degree of crystallinity. The diffraction peak for SnO₂ on every sample is dominant and diffraction peak for SiC increases with increase of weight % of dopant used in each sample. The lattice values, a and c for each sample had been calculated. The value of a is in the range of 4.734 Å to 4.751 Å while the value of c is in the

range of 3.179 Å to 3.191 Å. The values obtained show that the structure of each sample produced is tetragonal and the structure of SnO₂ did not change with increase in dopant. The variation in the a and c values for SnO₂ dopant can be attributed to the strain in the crystal structure of the host material due to the presence of the dopant.

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